



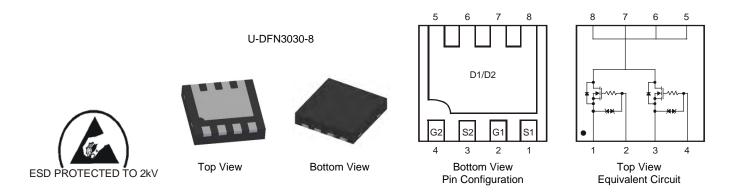
DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **ESD Protected Up To 2KV**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: U-DFN3030-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper lead frame. Solderable per MIL-STD-202, Method 208 @4
- Polarity: See Diagram
- Weight: 0.0172 grams (approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging		
DMG8601UFG-7	U-DFN3030-8	3000/Tape & Reel		

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



2N4 = Product marking code YYWW = Date code marking YY = Last digit of year (ex: 09 for 2009) WW = Week code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			VDSS	20	V
Gate-Source Voltage		Vgss	±12	V	
Continuous Drain Current (Note 5)	Steady State	TA = +25°C TA = +70°C	lo	6.1 5.2	А
Pulsed Drain Current			IDM	27	Α

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	Pb	0.92	W
Thermal Resistance, Junction to Ambient @TA = +25°C	Reja	136	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

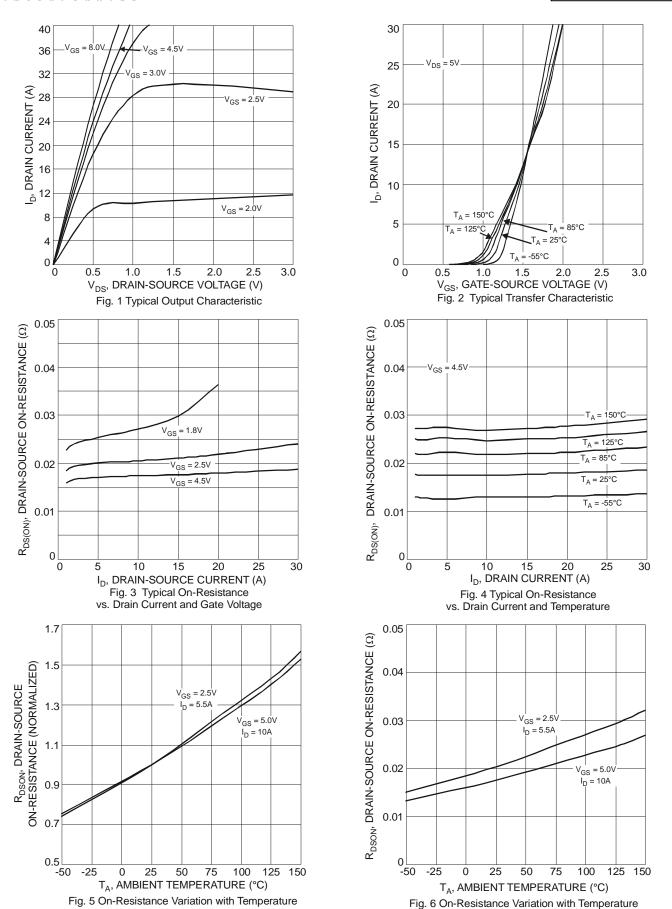
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = 25°C	I _{DSS}	-	-	1.0	μΑ	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	±10	μΑ	$V_{GS} = \pm 10V, V_{DS} = 0V$	
Gate-Source Breakdown Voltage	BV _{SGS}	±12	-	-	V	$V_{DS} = 0V, I_G = \pm 250 \mu A$	
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage	$V_{GS(th)}$	0.35	-	1.05	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
		-	17	23		$V_{GS} = 4.5V, I_D = 6.5A$	
Static Drain-Source On-Resistance	R _{DS (ON)}	-	20	27	mΩ	$V_{GS} = 2.5V, I_D = 5.5A$	
		-	25	34		$V_{GS} = 1.8V, I_D = 3.5A$	
Forward Transfer Admittance	Y _{fs}	-	10	-	S	$V_{DS} = 10V, I_{D} = 5A$	
Diode Forward Voltage	V _{SD}	-	0.7	1.0	V	$V_{GS} = 0V$, $I_S = 1A$	
DYNAMIC CHARACTERISTICS							
Input Capacitance	C _{iss}	-	143	-	pF		
Output Capacitance	Coss	-	74	1	pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	-	29	-	pF		
Gate Resistance	R_{g}	-	202	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Qq	-	8.8	-	nC		
Gate-Source Charge	Q _{gs}	-	1.4	-	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_{D} = 6.5A$	
Gate-Drain Charge	Q _{qd}	-	3.0	-	nC		
Turn-On Delay Time	t _{D(on)}	-	53	-	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$ $R_{L} = 10\Omega, R_{G} = 6\Omega$	
Turn-On Rise Time	t _r	-	78	-	ns		
Turn-Off Delay Time	t _{D(off)}	-	562	-	ns		
Turn-Off Fall Time	t _f	-	234	-	ns		

Notes:

- 5. Device mounted on FR-4 PCB with minimum recommended pad layout.
- 6. Short duration pulse test used to minimize self-heating effect.

DMG8601UFG
Document number: DS31788 Rev. 5 - 2







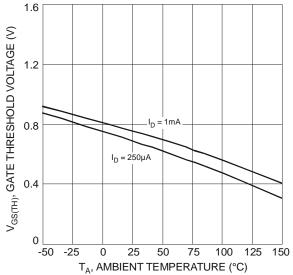


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

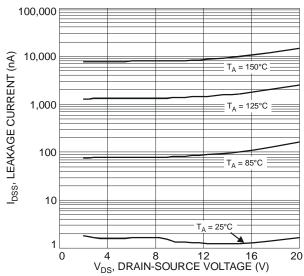


Fig. 9 Typical Leakage Current vs. Drain-Source Voltage

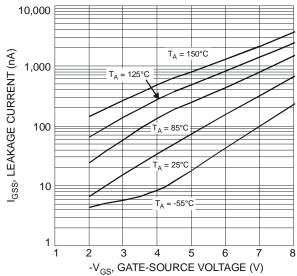
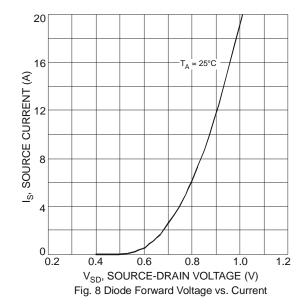


Fig. 11 Gate-Source Leakage Current vs. Voltage



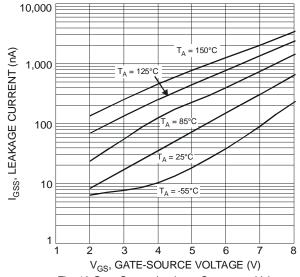
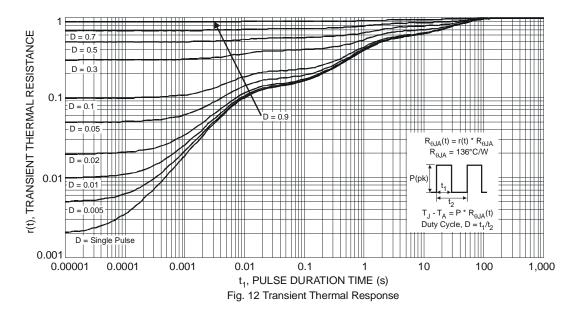


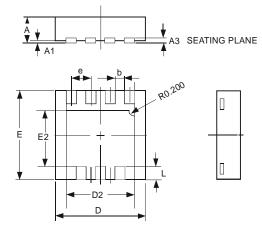
Fig. 10 Gate-Source Leakage Current vs. Voltage





Package Outline Dimensions

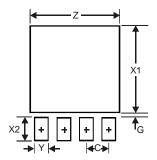
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



U-DFN3030-8				
Dim	Min	Max	Тур	
Α	0.57	0.63	0.60	
A1	0	0.05	0.02	
А3			0.15	
b	0.29	0.39	0.34	
D	2.90	3.10	3.00	
D2	2.19	2.39	2.29	
е			0.65	
Е	2.90	3.10	3.00	
E2	1.64	1.84	1.74	
L	0.30	0.60	0.45	
All Dimensions in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.59
G	0.11
X1	2.49
X2	0.65
Υ	0.39
С	0.65



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